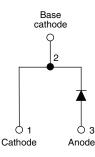
# VS-HFA25PB60-N3

Vishay Semiconductors

# HEXFRED<sup>®</sup> Ultrafast Soft Recovery Diode, 25 A



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PRIMARY CHARACTERISTICS								
I <sub>F(AV)</sub>	25 A							
V <sub>R</sub>	600 V							
V <sub>F</sub> at I <sub>F</sub>	1.3 V							
t <sub>rr</sub> (yp.	23 ns							
T <sub>J</sub> max.	150 °C							
Package	TO-247AC 2L							
Circuit configuration	Single							

## FEATURES

- Ultrafast and ultrasoft recovery
- Very low I<sub>RRM</sub> and Q<sub>rr</sub>
- Designed and qualified according to JEDEC<sup>®</sup>-JESD 47
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

#### BENEFITS

- Reduced RFI and EMI
- · Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

### DESCRIPTION

VS-HFA25PB60... is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 25 A continuous current, the VS-HFA25PB60... is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I<sub>BBM</sub>) and does not exhibit any tendency to "snap-off" during the t<sub>b</sub> portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA25PB60... is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Cathode to anode voltage	V <sub>R</sub>		600	V					
Maximum continuous forward current	I <sub>F</sub>	T <sub>C</sub> = 100 °C	25						
Single pulse forward current	I <sub>FSM</sub>	t <sub>p</sub> = 10 ms	225	A					
Maximum repetitive forward current	I <sub>FRM</sub>		100						
Movimum power dissinction	р	T <sub>C</sub> = 25 °C	151	w					
Maximum power dissipation	PD	T <sub>C</sub> = 100 °C	60	vv					
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +150	°C					

RoHS COMPLIANT HALOGEN

Revision: 16-Jun-2021

Document Number: 94064

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VS-HFA25PB60-N3



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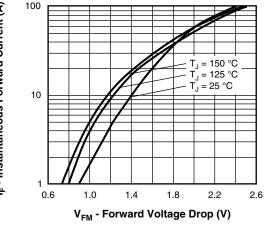
<b>ELECTRICAL SPECIFICATIONS</b> ( $T_J = 25 \ ^{\circ}C$ unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS		
Cathode to anode breakdown voltage	V <sub>BR</sub>	I <sub>R</sub> = 100 μA	600	-	-				
		I <sub>F</sub> = 25 A		-	1.3	1.7	V		
Maximum forward voltage	V <sub>FM</sub>	I <sub>F</sub> = 50 A	See fig. 1	-	1.5	2.0			
		I <sub>F</sub> = 25 A, T <sub>J</sub> = 125 °C		-	1.3	1.7			
Maximum reverse	1	$V_{R} = V_{R}$ rated	See fig. 2	-	1.5	20			
leakage current	I <sub>RM</sub>	$T_J = 125 \text{ °C}, V_R = 0.8 \text{ x } V_R \text{ rated}$		-	600	2000	μA		
Junction capacitance	CT	V <sub>R</sub> = 200 V	See fig. 3	-	55	100	pF		
Series inductance	LS	Measured lead to lead 5 mm from p	ackage body	-	12	-	nH		

<b>DYNAMIC RECOVERY CHARACTERISTICS</b> ( $T_J = 25 \text{ °C}$ unless otherwise specified)										
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS			
	t <sub>rr</sub>	$I_F = 1.0 \text{ A}, \ dI_F/dt = 200 \text{ A}$	A/μs, V <sub>R</sub> = 30 V	-	23	-				
Reverse recovery time See fig. 5, 10	t <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	50	75	ns A			
See lig. 5, 10	t <sub>rr2</sub>	T <sub>J</sub> = 125 °C	I <sub>F</sub> = 25 A dI <sub>F</sub> /dt = 200 A/μs V <sub>R</sub> = 200 V	-	105	160				
Peak recovery current	I <sub>RRM1</sub>	T <sub>J</sub> = 25 °C		-	4.5	10				
See fig. 6, 10	I <sub>RRM2</sub>	T <sub>J</sub> = 125 °C		-	8.0	15	A			
Reverse recovery charge	Q <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	112	375	nC			
See fig. 7, 10	Q <sub>rr2</sub>	T <sub>J</sub> = 125 °C		-	420	1200	no			
Peak rate of fall of recovery current during $t_b$ See fig. 8, 10	dl <sub>(rec)M</sub> /dt1	T <sub>J</sub> = 25 °C		-	250	-				
	dl <sub>(rec)M</sub> /dt2	T <sub>J</sub> = 125 °C		-	160	-	A/µs			

THERMAL - MECHANICAL SPECIFICATIONS									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Lead temperature	T <sub>lead</sub>	0.063" from case (1.6 mm) for 10 s	-	-	300	°C			
Thermal resistance, junction to case	R <sub>thJC</sub>		-	-	0.83				
Thermal resistance, junction to ambient	R <sub>thJA</sub>	Typical socket mount	-	-	40	K/W			
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth, and greased	-	0.25	-				
Woight			-	6.0	-	g			
Weight			-	0.21	-	oz.			
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)			
Marking device		Case style TO-247AC 2L			5DB60				
Marking device		Case style TO-247AC modified	HFA25PB60						



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Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

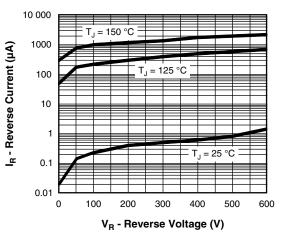


Fig. 2 - Typical Reverse Current vs. Reverse Voltage

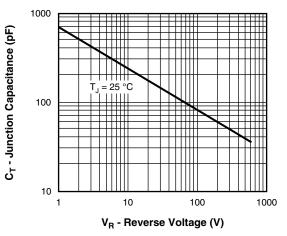


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

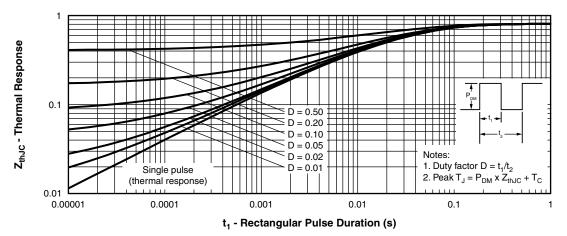


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics

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SHAY



140

# $\begin{array}{c} 1400 \\ I_{F} = 50 \text{ A} \\ I_{F} = 25 \text{ A} \\ I_{F} = 10 \text{ A} \\ 1000 \end{array}$

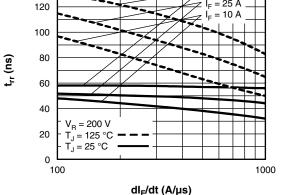


Fig. 5 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt

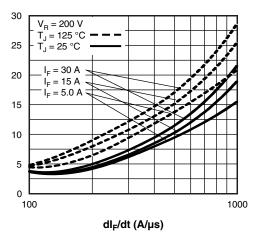
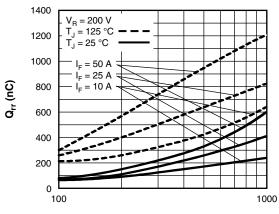


Fig. 6 - Typical Recovery Current vs. dl<sub>F</sub>/dt



**VS-HFA25PB60-N3** 

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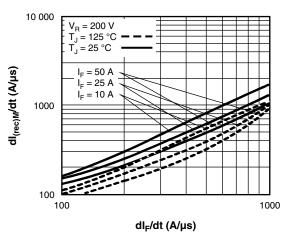
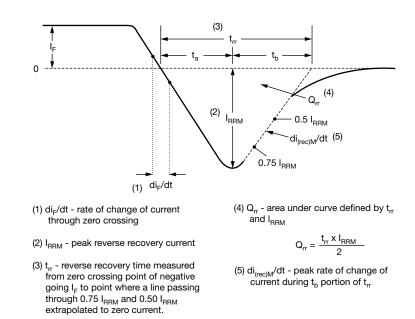


Fig. 8 - Typical  $dI_{(rec)M}/dt$  vs.  $dI_F/dt$ 



#### Fig. 9 - Reverse Recovery Waveform and Definitions

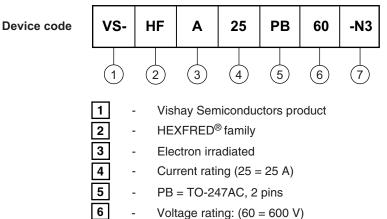
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I<sub>RR</sub> (A)





#### **ORDERING INFORMATION TABLE**



Current rating (25 = 25 A) -

- PB = TO-247AC, 2 pins -
- Voltage rating: (60 = 600 V)\_
- 7 Environmental digit: -

-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

ORDERING INFORMATION (Example)									
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION						
VS-HFA25PB60-N3	25	500	Antistatic plastic tube						

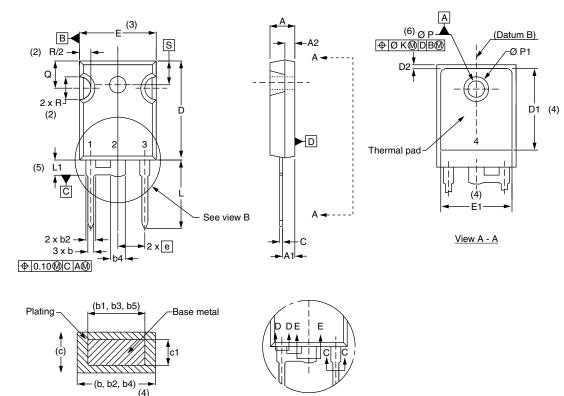
LINKS TO RELATED DOCUMENTS							
Dimensions	TO-247AC 2L	www.vishay.com/doc?96144					
Dimensions	TO-247AC modified	www.vishay.com/doc?95541					
Part marking information	TO-247AC 2L	www.vishay.com/doc?95648					
	TO-247AC modified	www.vishay.com/doc?95442					
SPICE model		www.vishay.com/doc?96665					



Vishay Semiconductors

# TO-247AC modified - 50 mils L/F

#### **DIMENSIONS** in millimeters and inches



Section C - C, D - D, E - E

View B
--------

SYMBOL	MILLIN	IETERS	INC	INCHES			
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES		
А	4.65	5.31	0.183	0.209			
A1	2.21	2.59	0.087	0.102			
A2	1.17	1.37	0.046	0.054			
b	0.99	1.40	0.039	0.055			
b1	0.99	1.35	0.039	0.053			
b2	1.65	2.39	0.065	0.094			
b3	1.65	2.34	0.065	0.092			
b4	2.59	3.43	0.102	0.135			
b5	2.59	3.38	0.102	0.133			
с	0.38	0.89	0.015 0.035				
c1	0.38	0.84	0.015	0.033			
D	19.71	20.70	0.776	0.815	3		
D1	13.08	-	0.515	-	4		

SYMBOL	MILLIN	IETERS	INC	HES	NOTES	
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES	
D2	0.51	1.35	0.020	0.053		
E	15.29	15.87	0.602	0.625	3	
E1	13.46	-	0.53	-		
е	5.46	BSC	0.215	BSC		
ØК	0.254		0.010			
L	14.20	16.10	0.559	0.634		
L1	3.71	4.29	0.146	0.169		
ØP	3.56	3.66	0.14	0.144		
Ø P1	-	7.39	-	0.291		
Q	5.31	5.69	0.209	0.224		
R	4.52	5.49	0.178	0.216		
S	5.51 BSC		0.217			

#### Notes

- <sup>(1)</sup> Dimensioning and tolerance per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- <sup>(4)</sup> Thermal pad contour optional with dimensions D1 and E1
- <sup>(5)</sup> Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- <sup>(7)</sup> Outline conforms to JEDEC<sup>®</sup> outline TO-247 with exception of dimension c and Q

Revision: 20-Apr-17

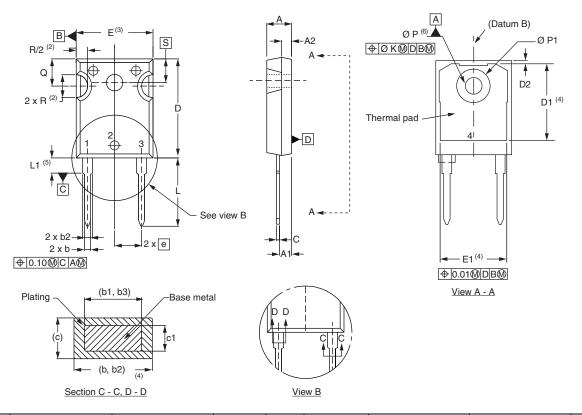
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**Vishay Semiconductors** 

TO-247AC 2L

#### **DIMENSIONS** in millimeters and inches



SYMBOL	MILLIN	IETERS	INC	HES	NOTES	SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STINDUL	MIN.	MAX.	MIN.	MAX.	NOTES	STIVIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
A	4.65	5.31	0.183	0.209		E	15.29	15.87	0.602	0.625	3
A1	2.21	2.59	0.087	0.102		E1	13.46	-	0.53	-	
A2	1.17	1.37	0.046	0.054		e	5.46	BSC	0.215	BSC	
b	0.99	1.40	0.039	0.055		ØК	0.2	254	0.0	)10	
b1	0.99	1.35	0.039	0.053		L	14.20	16.10	0.559	0.634	
b2	1.65	2.39	0.065	0.094		L1	3.71	4.29	0.146	0.169	
b3	1.65	2.34	0.065	0.092		ØР	3.56	3.66	0.14	0.144	
С	0.38	0.89	0.015	0.035		Ø P1	-	7.39	-	0.291	
c1	0.38	0.84	0.015	0.033		Q	5.31	5.69	0.209	0.224	
D	19.71	20.70	0.776	0.815	3	R	4.52	5.49	0.178	0.216	
D1	13.08	-	0.515	-	4	S	5.51 BSC 0.217 BSC				
D2	0.51	1.35	0.020	0.053							
NI - I											

#### Notes

<sup>(1)</sup> Dimensioning and tolerancing per ASME Y14.5M-1994

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<sup>(7)</sup> Outline conforms to JEDEC<sup>®</sup> outline TO-247 with exception of dimension Q

Revision: 07-Dec-17

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